

NOTES:

1. MATERIALS

HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0

COLOR: BLACK

EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0

COLOR: SEE TABLE

TERMINAL - COPPER ALLOY

2. PLATING - SEE TABLE IN SHEET 5 & 6.

3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.
(MEASURED OVER P.C. PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.

5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.

6. PRODUCT SHALL BE PACKED IN TRAY.

7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

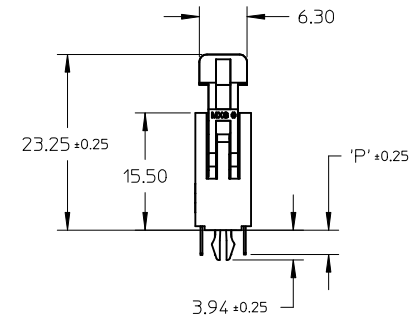
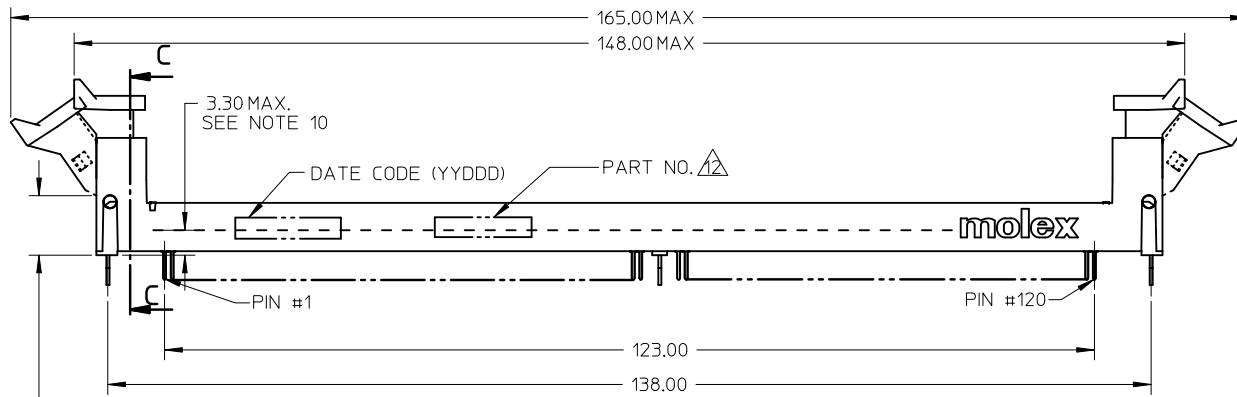
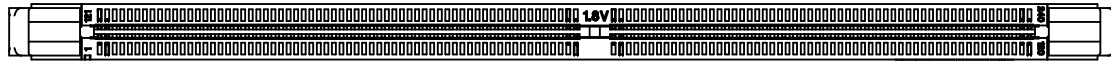
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.

9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.

10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

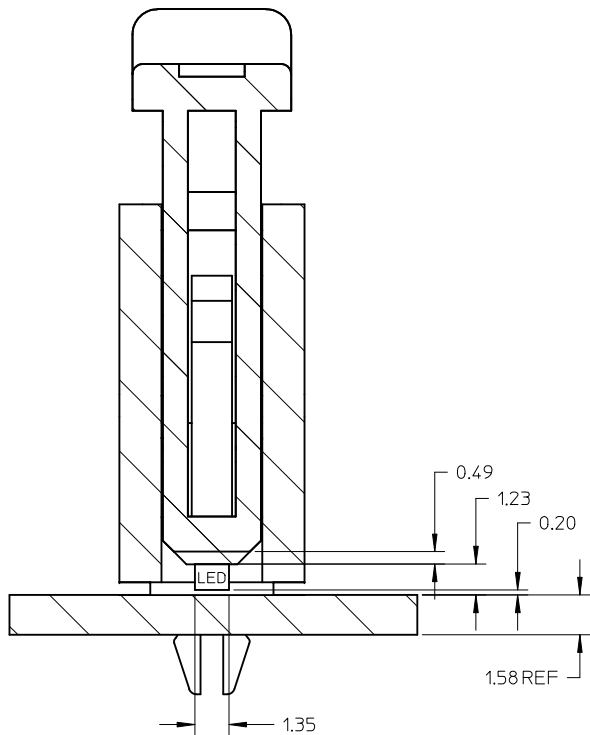
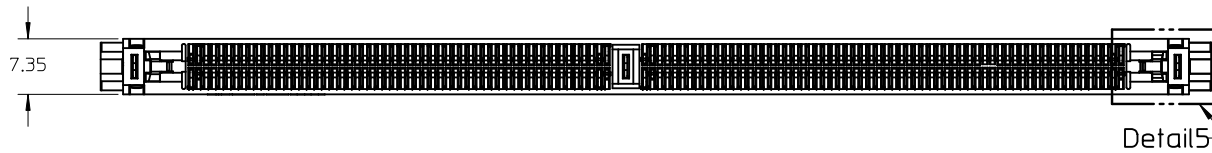
▲ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



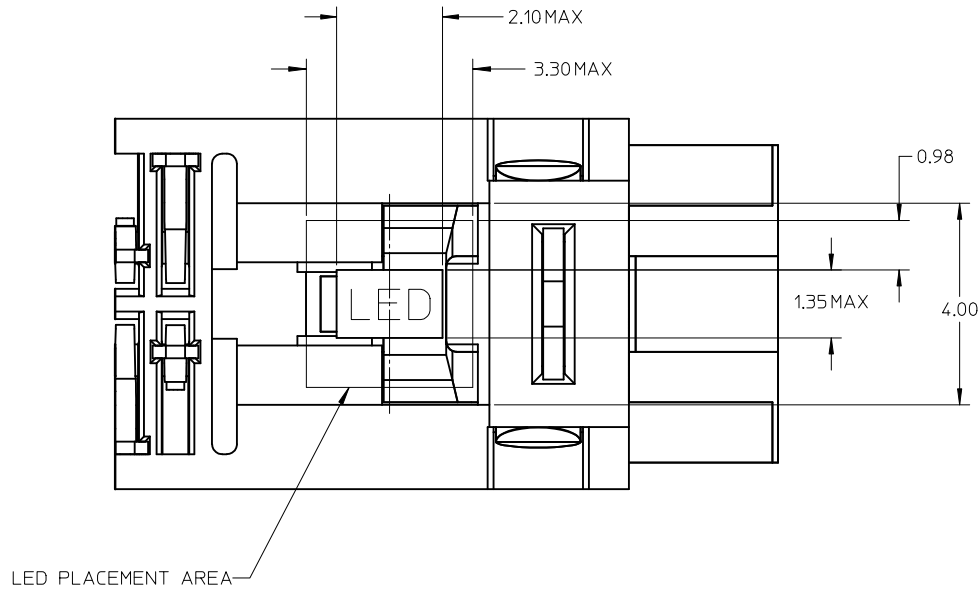
5.00 MIN
LATCH KEEP
OUT AREA

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $\nabla_A=0$ $\nabla_C=0$ $\nabla_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS			
	2 PLACES	± 0.20	± ---	DSOH	2002/07/22	(FORKLOCK VERSION)				
	1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED				
		ANGULAR ± 5 °		SKTOH	2002/07/23	DOCUMENT NO. SD-87705-001				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 6				
D2	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1



SECTION C-C



LED PLACEMENT AREA

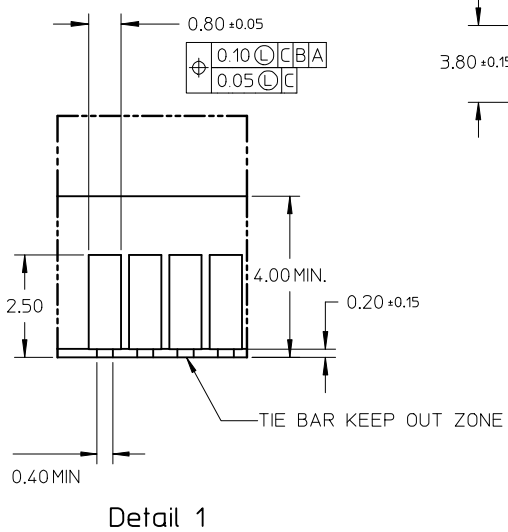
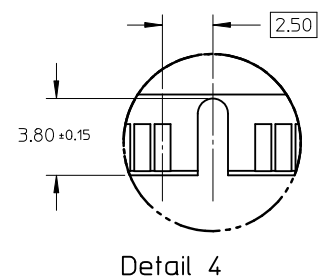
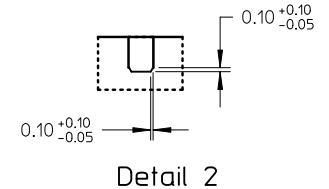
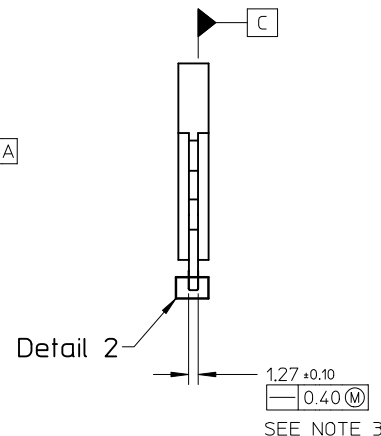
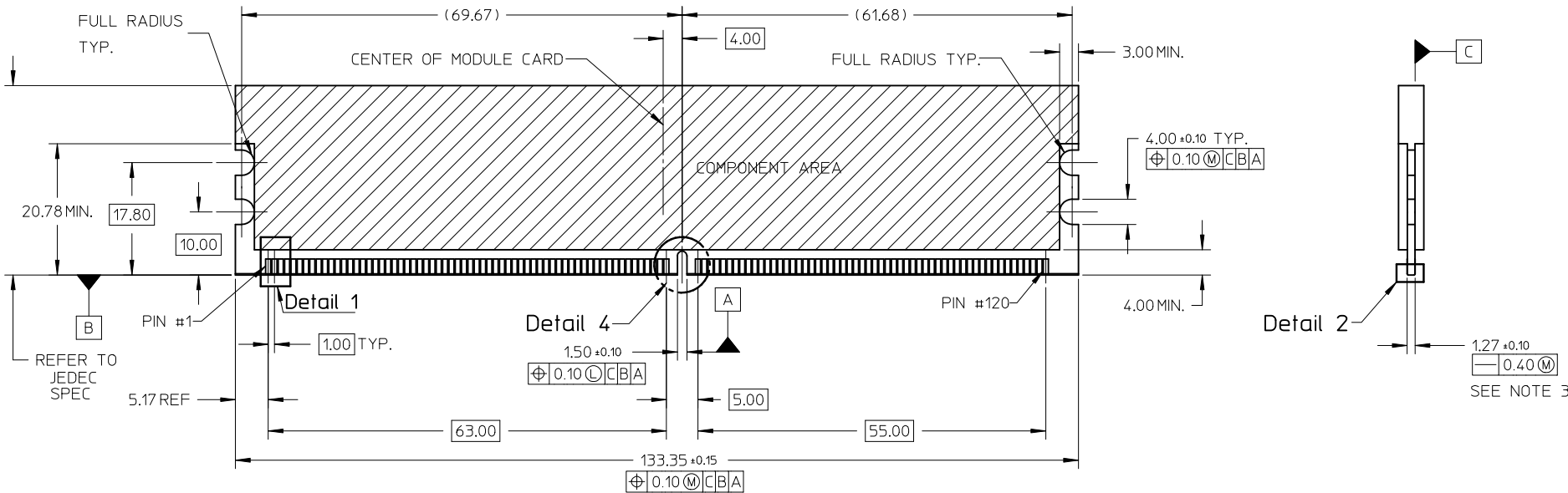
Detail 5

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH 2009/11/16 CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE MM ONLY DRAWN BY CGOH DATE 2002/05/09 CHECKED BY DS0H DATE 2002/07/22 APPROVED BY SKTOH DATE 2002/07/23	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		MOLEX INCORPORATED DOCUMENT NO. SD-87705-001
	MATERIAL NO.		SHEET NO. 2 OF 6			
	D2	REV	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT

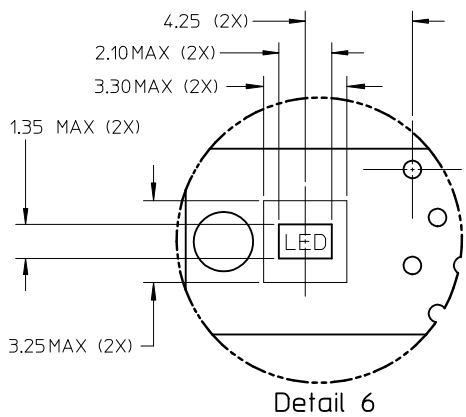


NOTES:
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

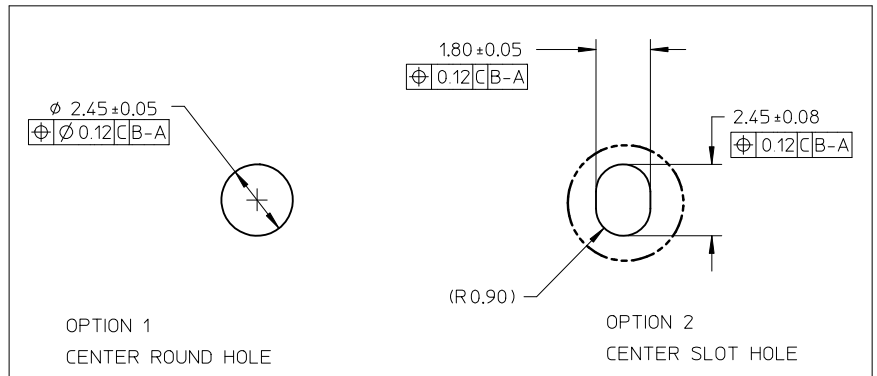
ADDED OPTION EC NO: S2012-0025 DRW: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
		3 PLACES ± --- ± ---		CHECKED BY DSOH	DATE 2002/07/22	MOLEX INCORPORATED			
		2 PLACES ± 0.20 ± ---		APPROVED BY SKTOH	DATE 2002/07/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87705-001	SHEET NO. 3 OF 6	
1 PLACE ± --- ± ---		ANGULAR ± 5 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

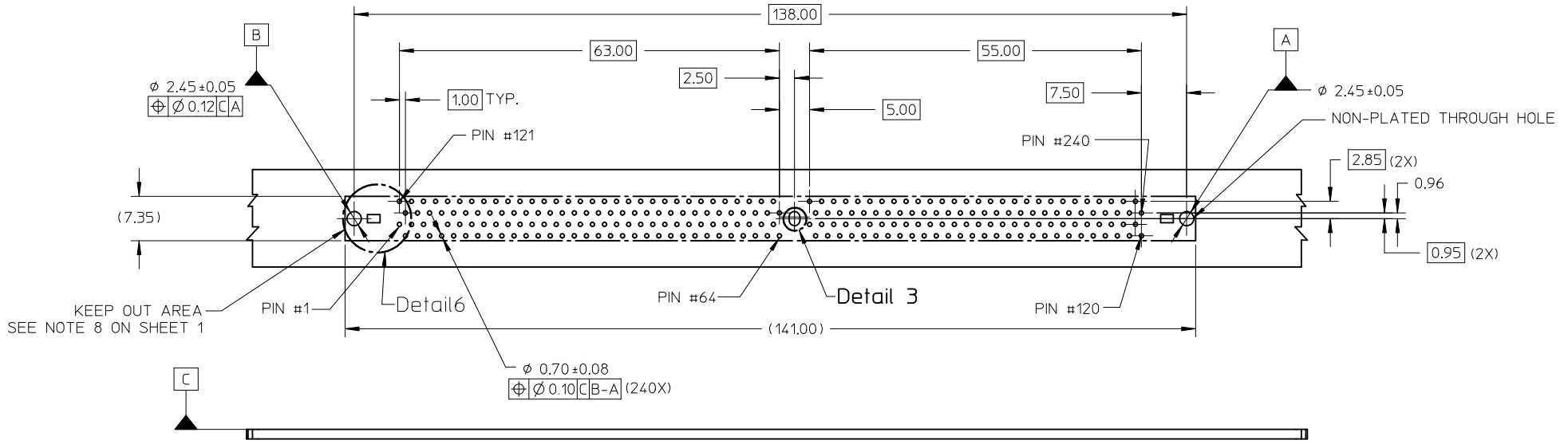


Detail 6



Detail 3

(SEE RECOMMENDED THICKNESS IN TABLE)
RECOMMENDED PCB LAYOUT
CONNECTOR SIDE



KEEP OUT AREA
SEE NOTE 8 ON SHEET 1

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH 2009/11/16 CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$F_A=0$ $F_G=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DSOH DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23	TITLE	DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
				MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-87705-001	SHEET NO.	4 OF 6	

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR	LUBRICATION
87705-0021	CENTER (1.8V)	2.67	1.57	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL	NO
87705-1021		3.18	2.36			
87705-1053		3.66				
87705-0031		2.67	1.57	0.03uM / 1 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1031		3.18	2.36			
87705-0051		2.67	1.57	0.76uM / 30 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1051		3.18	2.36			
87705-3061						YES

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH 2009/11/16 CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH	MM ONLY	NTS	METRIC	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DSOH DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87705-001	SHEET NO. 5 OF 6	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-5051	CENTER (1.8V)	2.67	1.57	0.76μM / 30 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	CLEAR
87705-5151		3.18	2.36		
87705-6151		3.18	2.36	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	
87705-9101		2.67	1.57	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	

ADDED OPTION EC NO: S2012-0025 2009/11/16 DRW: CTEH CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	REV D2	DESCRIPTION QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
					mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
			4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22					
			3 PLACES	± ---	± ---	APPROVED BY SKTOH		DATE 2002/07/23	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87705-001	
2 PLACES	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
1 PLACE	± ---	± ---	ANGULAR ± 5 °									